HK Tech 300 Seed Fund Application Guidelines

About HK Tech 300 Seed Fund
The University sets up the HK Tech 300 Seed Fund under the HK Tech 300 Programme (“Programme”). It gives our students a chance to open their minds to endless possibilities and turn their imagination into reality. The HK Tech Seed Fund offers the first funding support at HK$100,000 for successful teams to be nurtured into strong candidates eligible to apply for more substantial funding support. It also kicks start the other incubation initiatives including co-working space, business meet-ups with major chambers, as well as mentors and other support such as milestone review and consultation, etc. to help the project teams along their road to entrepreneurship. It is an excellent educational and growth opportunity for our students and youth in Hong Kong.

Eligibility
1. The Person-in-Charge (“PIC”) of the project team forming must be associated with CityU in any one of the following capacities at the time of application:
   (i) CityU student
   (ii) CityU research staff
   (iii) CityU alumna/us (who has graduated normally within 8 years as of the date of application)
   (iv) Others (when the team is championing commercial use of CityU’s intellectual property)

2. The PIC is responsible for overseeing the project team’s operations and serving as the team's liaison person.

3. Each project team must have at least two members, including the PIC.

4. The applicant or members allow applying for the Programme twice for a different project funded or invested by HK Tech 300 in any role but needs to complete one before starting the others.

5. The applicant or members should not apply more than 1 project in the same Cohort.

Funding Arrangement
6. Each approved project team can receive funding support at an amount of HK$100,000.

7. The funding period and terms will be shown in the HK Tech 300 Seed Fund Agreement to be signed, and the release of funding is subject to the stipulated requirements. The project team has to finish the agreed milestones within the funding period and must submit interim
and final reports together with the corresponding statements of expenditures as required before the funding is released to the PIC in three installments as follows –

- 1st installment of up to HK$20,000: within 45 days after signing the HK Tech 300 Seed Fund Agreement
- 2nd installment of up to HK$40,000: after submission and approval of an interim report and confirmation of the completion of the relevant milestones by an assessment committee assigned by the University
- 3rd installment of up to HK$40,000: within 45 days upon satisfactory project completion (including satisfactory achievement of all milestones and production of all deliverables, if any) and acceptance of the final report by an assessment committee assigned by the University

**Application Procedure**

8. Please apply online via [https://cityuhk.questionpro.com/hktech300seedfund](https://cityuhk.questionpro.com/hktech300seedfund) with all supporting documents uploaded in PDF format.

**Assessment and Selection**

9. Shortlisted applicants will be invited to an interview by a selection panel comprising CityU and external assessors with relevant expertise and experience. The selection criteria include:

   (i) Innovative product/ solutions for a real-life problem
   (ii) High chance to meet the market needs and get the interest from industry/ customer/ investor
   (iii) Clearly defined direction and roadmap of product/ solutions development
   (iv) Product/ Solutions having potential commercialization opportunity
   (v) Milestones set being achievable against the proposed timeline

10. Preference will be given to inventions/ technologies to be developed based on CityU’s intellectual property.

**Breach of Guidelines**

11. CityU reserves the right to revise the HK Tech 300 Seed Fund application guidelines without giving any prior notice. Any breach of the guidelines may lead to immediate termination of the application and any subsequent funding.

**Enquiries**

Email: hktech300.seed@cityu.edu.hk

(Updated as of October 2023)